

In the Specification:

Please replace the first full paragraph on page 4 with the following paragraph.

B1
A cross section of a part of a two piece mold is shown in Fig. 2. The mold has an upper part 30, a lower part 28, a cavity 34 in the upper part 30 of the mold and a recess 29 in the lower part 28 of the mold. The substrate 10 with the integrated circuit element 12 attached fits into the recess 29 of the lower part 28 of the mold. As can be seen in Fig. 2, the input/output balls have not been formed on the substrate at this point in the processing. A mold runner channel 32 is formed in the upper part of the mold 30 and forms a path for the uncured encapsulant to flow into the cavity 34 in the upper part 30 of the mold. Fig. 3 is a plan view of the upper part 30 of the mold, taken along line 3-3' of Fig. 2, showing the cavity 34 and the mold runner channel 32.

Please replace the second paragraph on page 12 with the following paragraph.

B2
Figs. 9 and 10 show the encapsulated package with the mold runner and barrier material removed, except for a small remainder 35 of the mold runner. Fig. 9 shows the top view of the substrate and Fig. 9 a cross section view taken along line 10-10' of Fig. 9.